ASSOCIATION CONNEC	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under bot international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Typ Distribute													
Supplier Info	rmation														
Company name*			Company un	Company unique ID			Unique ID Authority					Response Date*			
nsemi											2025-08	2025-08-01			
				Title - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-Env-Ste	ewards		Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
uthorized Repr	esentative*	Title - Repre	Title - Representative			Phone - Representative*				Email -	Email - Representative*				
Product-Env-Ste	ewards	Product Enviro Compliance			1	NA				Produc	Product-Env-Stewards@onsemi.com				
Reque	quester Item Number Mfr Iter		m Number Mfr Item Name				Effective Date	Version	Ma	Manufacturing Site		Weight*	* UOM	Unit Type	
		USB1T20		0MTCX USB1.1 Transceiver			2025-08-01 PH4			54.823 mg		Each			
Ianufacturi n	ng Proccess Informati	on													
Termir	rminal Plating / Grid Array Material		Terminal Base Alloy J-		J-STD-020 MS	SL Rating	Peak Proces	ak Process Body Temperature Max Time at Pea		eak Tempera	ture N	umber of Reflow Cy	iber of Reflow Cycles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260	C		30		nds 3			
Comments								•							
vel 1 - maximu	n time at peak temperatur	e during so	oldering is 10-3	30 seconds											
	ation regarding material c														

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt Weig	ght Unit of Measure
Die	0.496	mg	Supplier	Silicon (Si)	7440-21-3	0.496	6 mg
Die Attach	0.055	mg		Bismaleimide Resin	proprietary data	0.009	ol mg
			Supplier	Other Additive Agents	Proprietary Data	0.001	19 mg
			Supplier	Silver (Ag)	7440-22-4	0.044	1 mg
Lead Frame	21.563	mg	Supplier	Magnesium (Mg)	7439-95-4	0.032	2 mg
			Supplier	Silicon (Si)	7440-21-3	0.14	mg
			В	Nickel (Ni)	7440-02-0	0.691	l mg
			Supplier	Copper (Cu)	7440-50-8	20.7	mg
Mold Compound-Black	32.2	mg		Epoxy resin	proprietary data	3.059	mg
			Supplier	Phenol Resin	Proprietary Data	1.61	mg
			Supplier	Carbon Black (C)	1333-86-4	0.161	l mg
			Supplier	Fused Silica (SiO2)	60676-86-0	27.37	7 mg
Plating	0.161	mg	Supplier	Palladium (Pd)	7440-05-3	0.005	5 mg
-			В	Nickel (Ni)	7440-02-0	0.153	3 mg
			Supplier	Gold (Au)	7440-57-5	0.003	3 mg
Wire Bond - Au	0.348	mg	Supplier	Gold (Au)	7440-57-5	0.348	B mg